

IN THE CLAIMS:

1. (Previously Presented) A modem module for connecting to a carrier assembly, comprising:
circuitry for interfacing with a telephone line; and

one or more solder pads for connecting a signal line of said modem module to
said carrier assembly.

2. (Original) The modem module of claim 1, further comprising a tip/ring connector for
interfacing with said telephone line.

3. (Original) The modem module of claim 1, further comprising a connection to a tip/ring
connector.

4. (Original) The modem module of claim 1, wherein said carrier assembly is a motherboard.

5. (Original) The modem module of claim 1, wherein said one or more solder pads are soldered
to corresponding one or more solder pads on said carrier assembly.

6. (Original) The modem module of claim 1, wherein said modem assembly is fabricated on a
printed circuit board.

7. (Original) The modem module of claim 1, wherein said modem assembly is an integrated
device.

8. (Previously Presented) A method for fabricating a modem module for connection to a carrier
assembly, comprising the steps of:

providing circuitry on a printed circuit board for interfacing with a telephone line;
and

providing one or more solder pads on said printed circuit board for connecting a
signal line of said modem module to said carrier assembly.

9. (Original) The method of claim 8, further comprising the step of providing a tip/ring connector for interfacing with said telephone line.

10. (Original) The method of claim 8, further comprising the step of connecting to a tip/ring connector.

11. (Original) The method of claim 8, wherein said carrier assembly is a motherboard.

12. (Original) The method of claim 8, further comprising the step of soldering said one or more solder pads to corresponding one or more solder pads on said carrier assembly.

13. (Original) The method of claim 8, further comprising the step of fabricating said modem assembly on a printed circuit board.

14. (Previously Presented) A printed circuit board, comprising:
modem circuitry for interfacing with a telephone line; and
one or more solder pads for connecting a signal line of said modem circuitry to a carrier assembly.

15. (Original) The printed circuit board of claim 14, further comprising a tip/ring connector for interfacing with said telephone line.

16. (Original) The printed circuit board of claim 14, further comprising a connection to a tip/ring connector.

17. (Original) The printed circuit board of claim 14, wherein said carrier assembly is a motherboard.

18. (Original) The printed circuit board of claim 14, wherein said one or more solder pads are soldered to corresponding one or more solder pads on said carrier assembly.

19. (Original) The printed circuit board of claim 14, wherein said modem assembly is fabricated on a printed circuit board.

20. (Original) The printed circuit board of claim 14, wherein said modem assembly is an
5 integrated device.